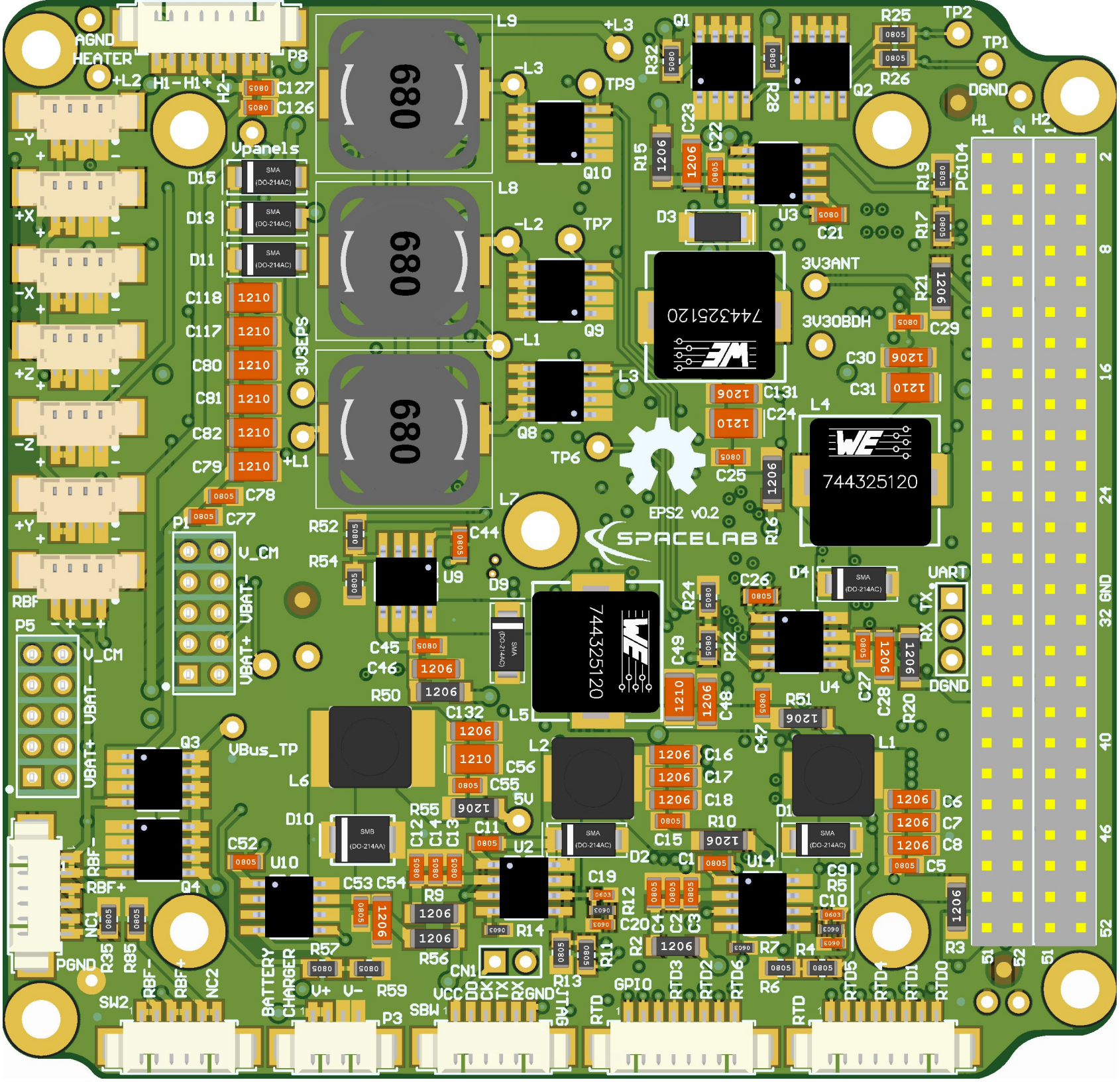
AGND
HEATER
P8
H1-H1+
H2
C127
C126
Vpanels
D15
D13
D11
C118
C117
C80
C81
C82
C79
C78
C77
3V3EPS
+L1
-L1
+L2
-L2
+L3
-L3
L9
L8
L7
L3
L4
L5
L6
L1
L2
Q1
Q2
Q3
Q4
Q8
Q9
Q10
TP1
TP2
TP6
TP7
TP9
DGND
R25
R26
R28
R32
R15
R19
R17
R21
R16
R20
R51
R52
R54
R50
R55
R9
R56
R57
R59
R10
R5
R3
R6
R7
R4
R11
R13
R14
R12
R2
C21
C22
C23
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C54
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C12
C13
C14
C15
C16
C17
C18
C19
C20
C1
C2
C3
C4
C6
C7
C8
C9
C10
C5
U3
U4
U9
U10
U14
U2
D3
D4
D9
D10
D1
D2
PC104
3V3ANT
3V3OBDH
744325120
EPS2 v0.2
SPACELAB
UART
TX
RX
DGND
P1
V_CM
VBAT-
VBAT+
P5
RBF
-Y
+X
-X
+Z
-Z
+Y
VBus_TP
5V
NC1
RBF-
RBF+
PGND
R35
R85
NC2
SW2
BATTERY CHARGER
V+
V-
P3
SBW
CN1
VCC
DO
CK
TX
RX
GND
JTAG
GPIO
RTD
RTD3
RTD2
RTD6
RTD5
RTD4
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RTD0
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H2
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52
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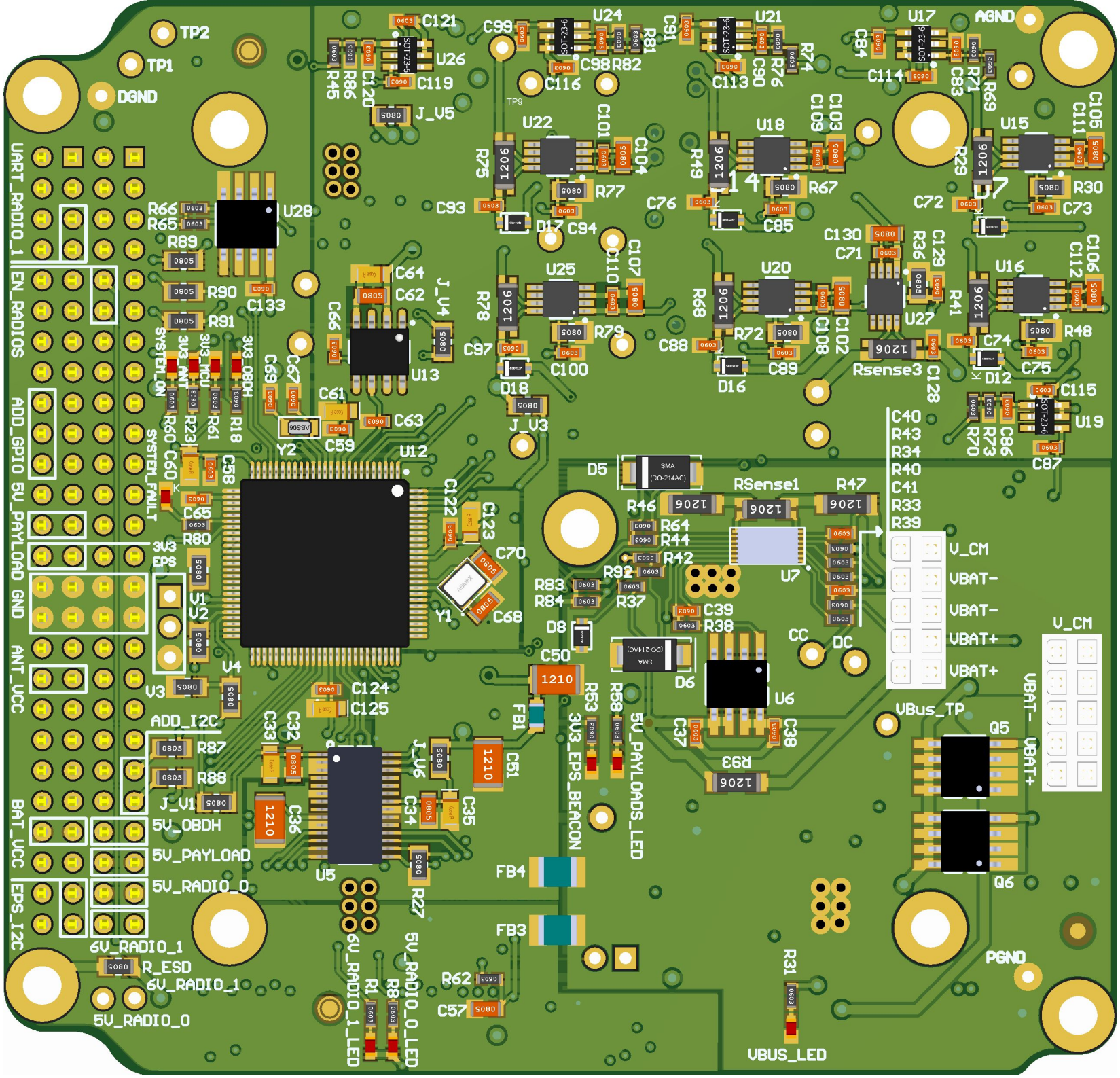
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TP1
DGND
AGND
PGND
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EN_RADIOS
ADD_GPIO
5V_PAYLOAD
GND
ANT_VCC
BAT_VCC
EPS_I2C
SYSTEM_ON
3V3_ANT
3V3_MCU
3V3_OBDH
SYSTEM_FAULT
3V3_EPS
ADD_I2C
5V_OBDH
5V_PAYLOAD
5V_RADIO_0
6V_RADIO_1
R_ESD
6V_RADIO_1
5V_RADIO_0
6V_RADIO_1_LED
5V_RADIO_0_LED
3V3_EPS_BEACON
5V_PAYLOADS_LED
VBUS_LED
VBus_TP
V_CM
VBAT-
VBAT-
VBAT+
VBAT+
V_CM
VBAT-
VBAT+
CC
DC
RSense1
Rsense3
U1
U2
U3
U4
U5
U6
U7
U12
U13
U15
U16
U17
U18
U19
U20
U21
U22
U24
U25
U26
U27
U28
Q5
Q6
Y1
Y2
D5
D6
D8
D12
D16
D17
D18
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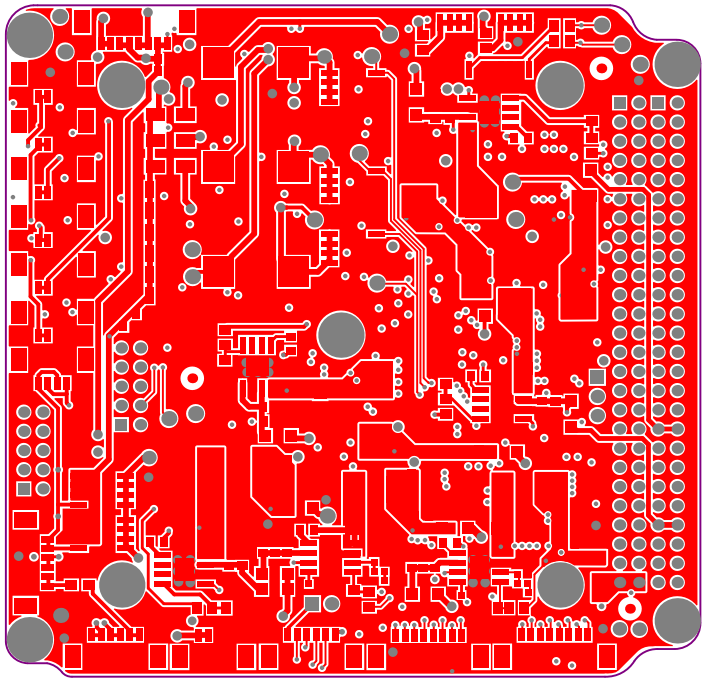
FB3
FB4
J_V1
J_V3
J_V4
J_V5
J_V6



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

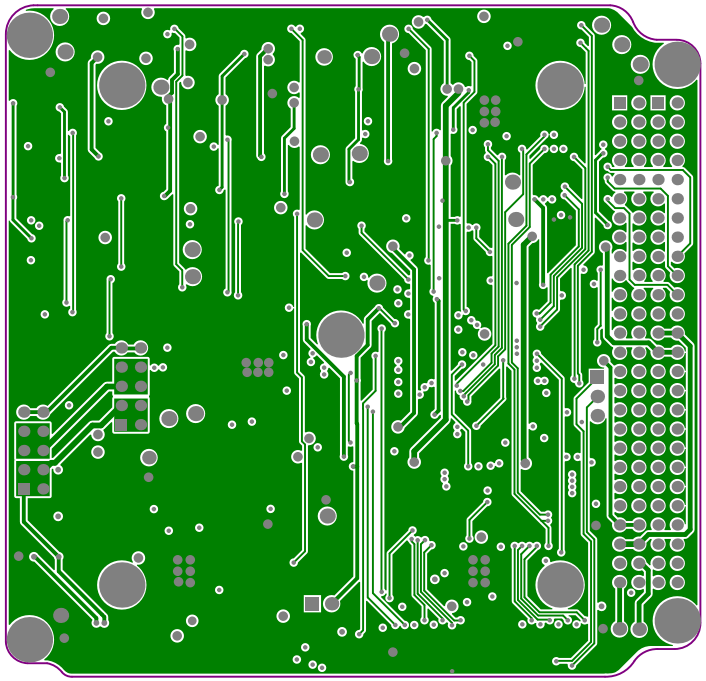
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Top Layer		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

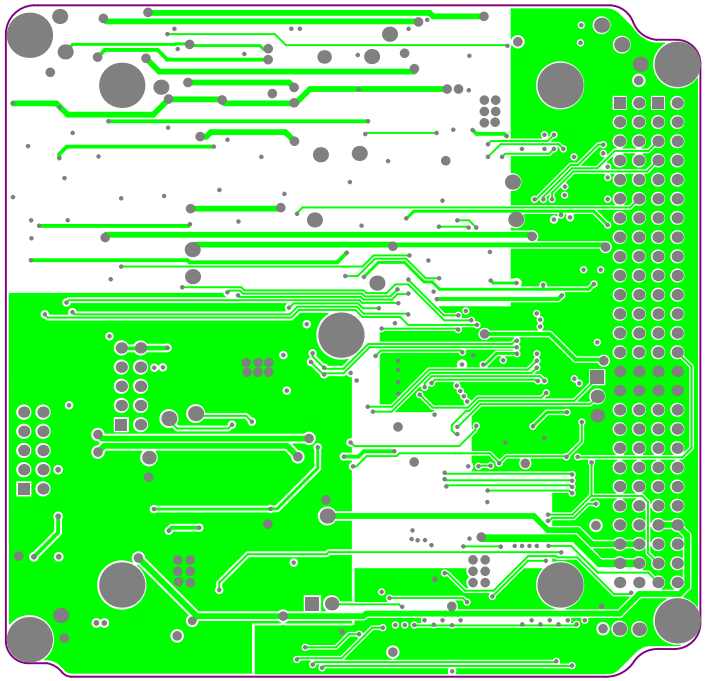
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Signal Layer 1		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

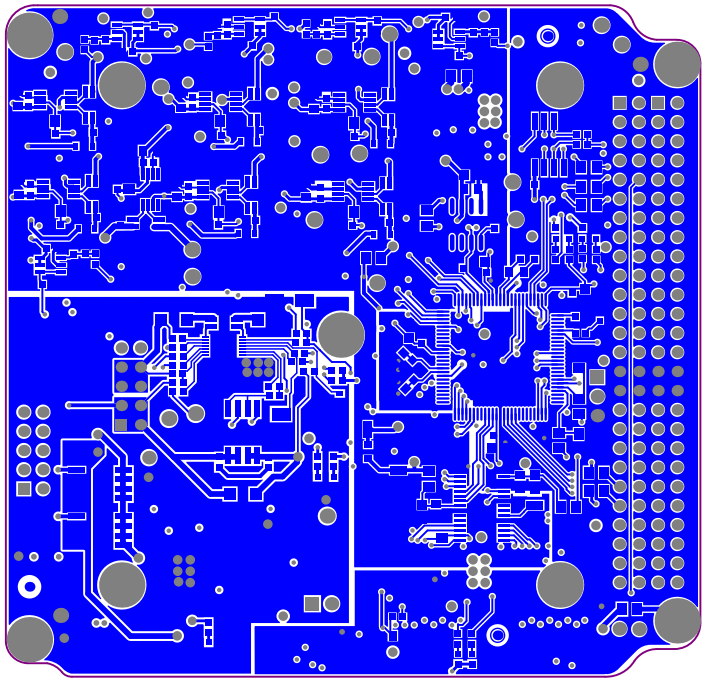
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Signal Layer 2		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

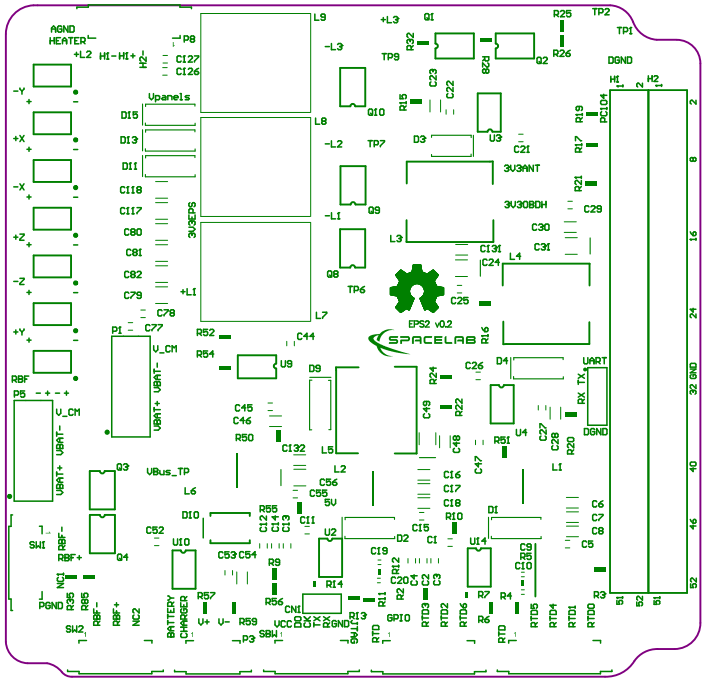
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Bottom Layer		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

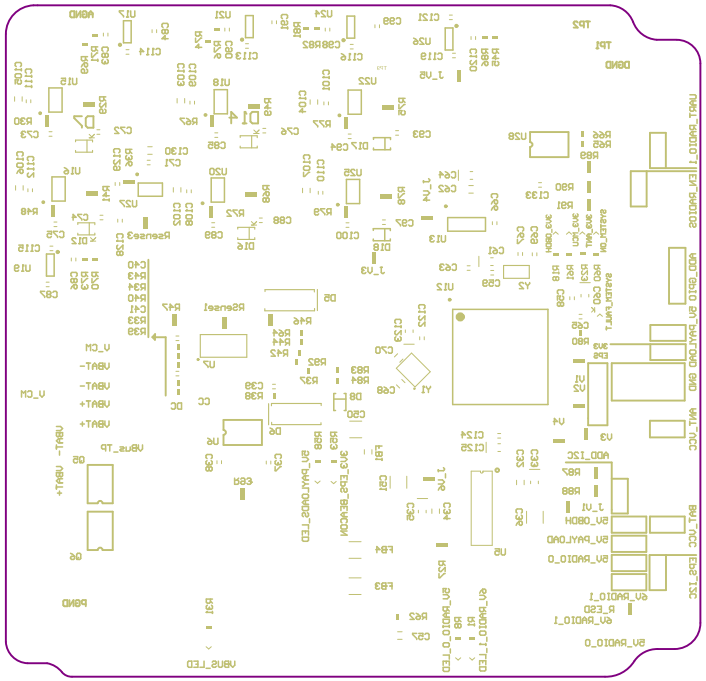
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Top Overlay		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

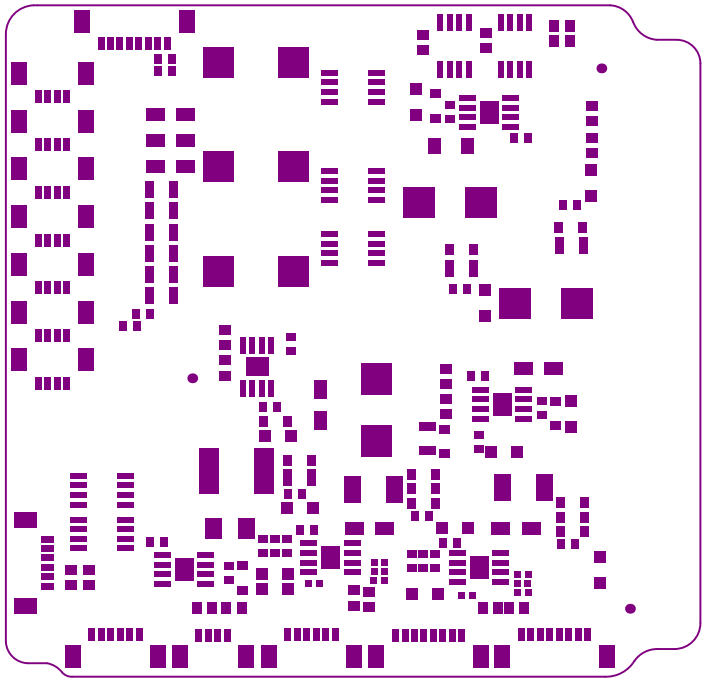
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Bottom Overlay		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

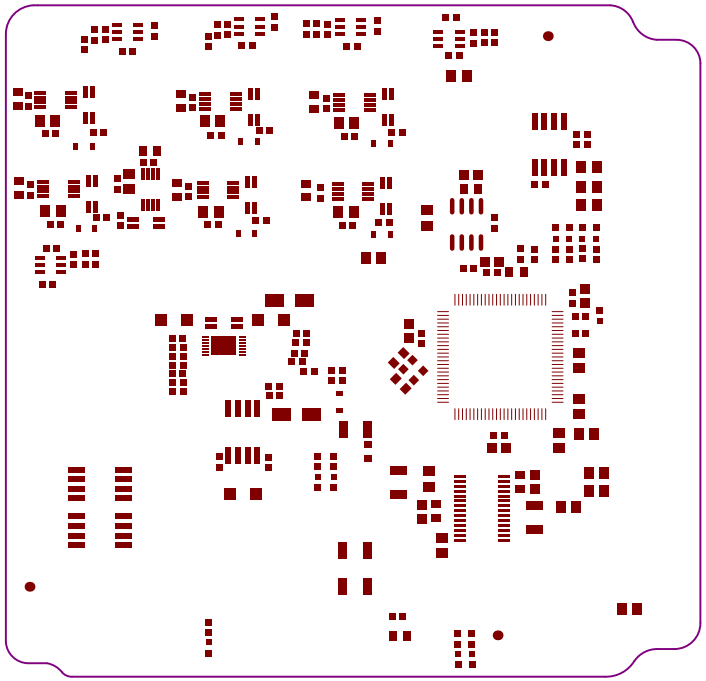
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Top Paste		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

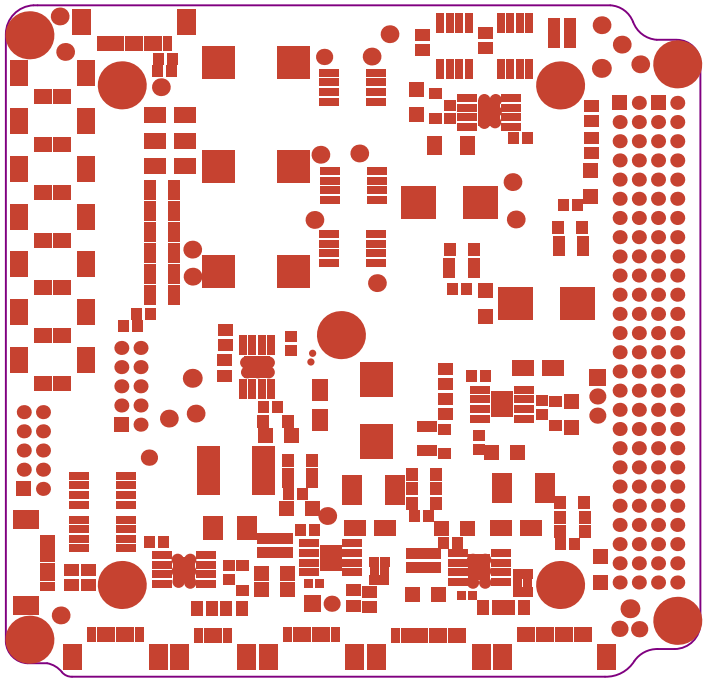
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Bottom Paste		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

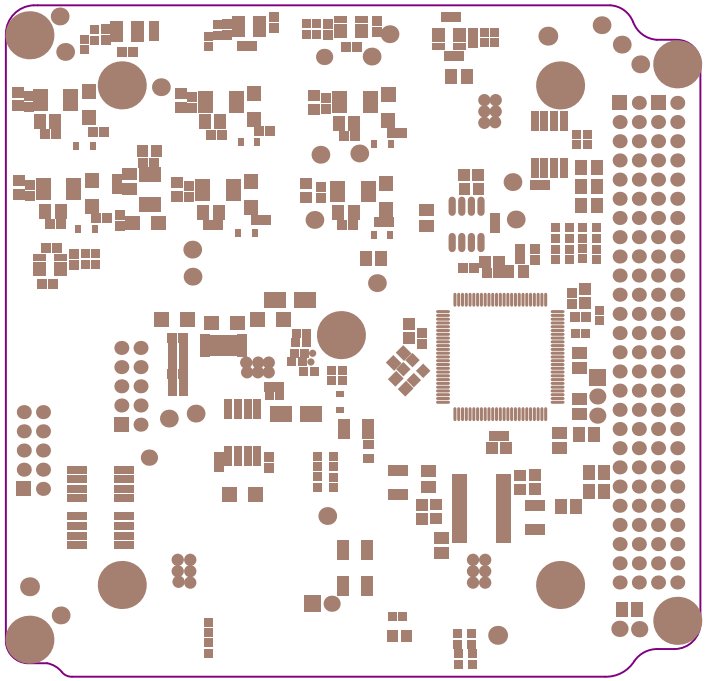
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Top Solder		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

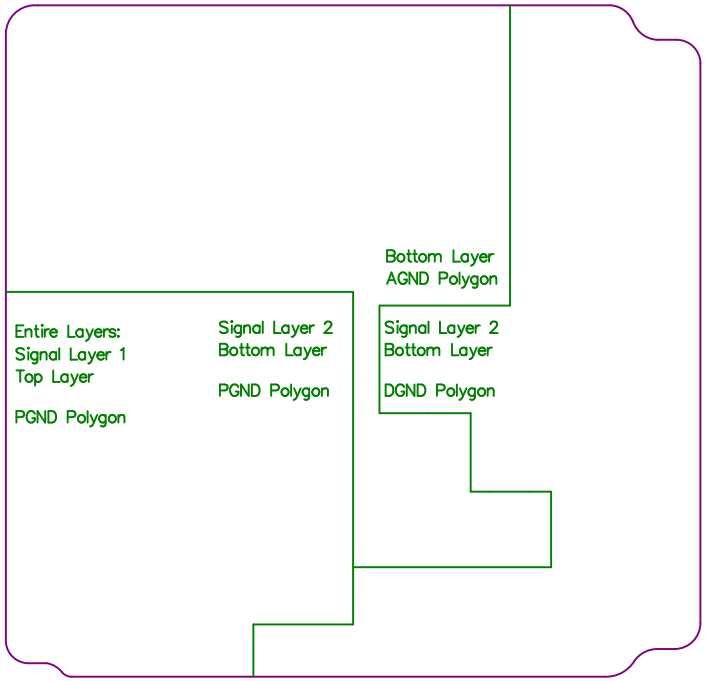
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Bottom Solder		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

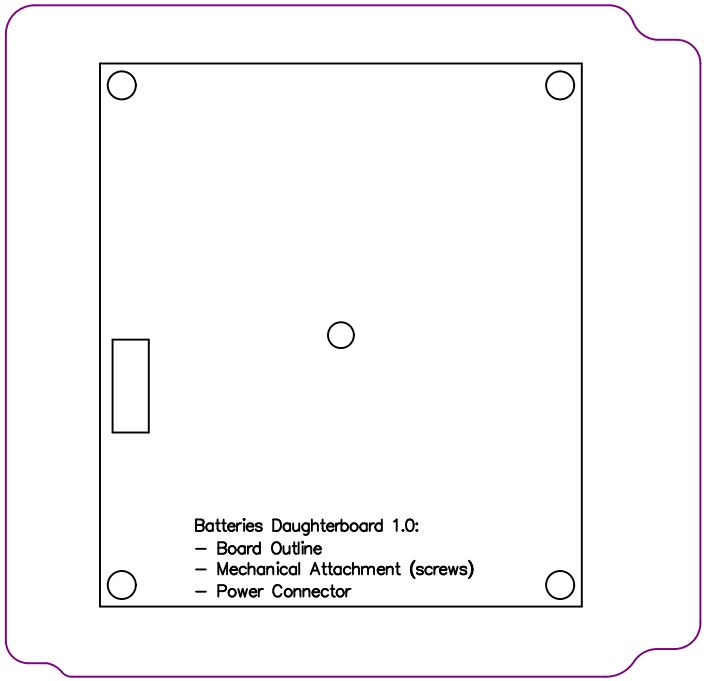
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Grounding Splits		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

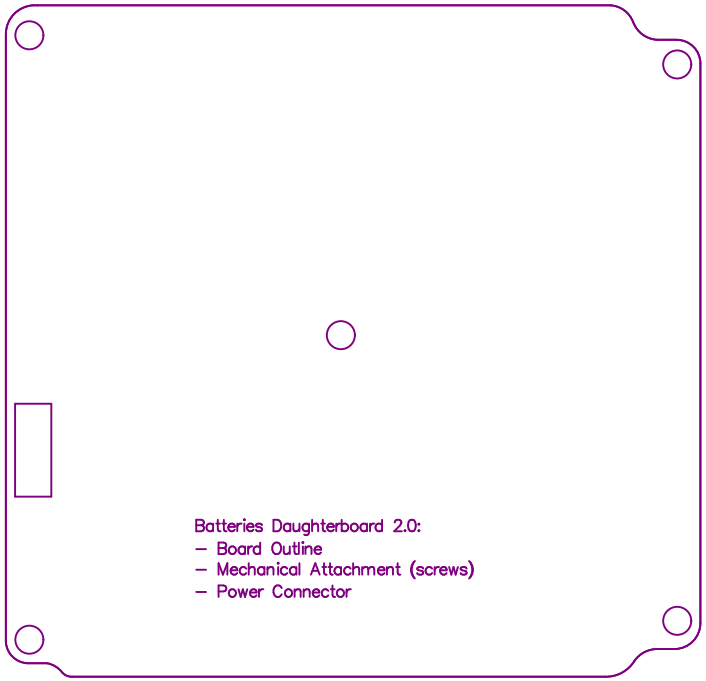
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Batteries Board 1.0		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

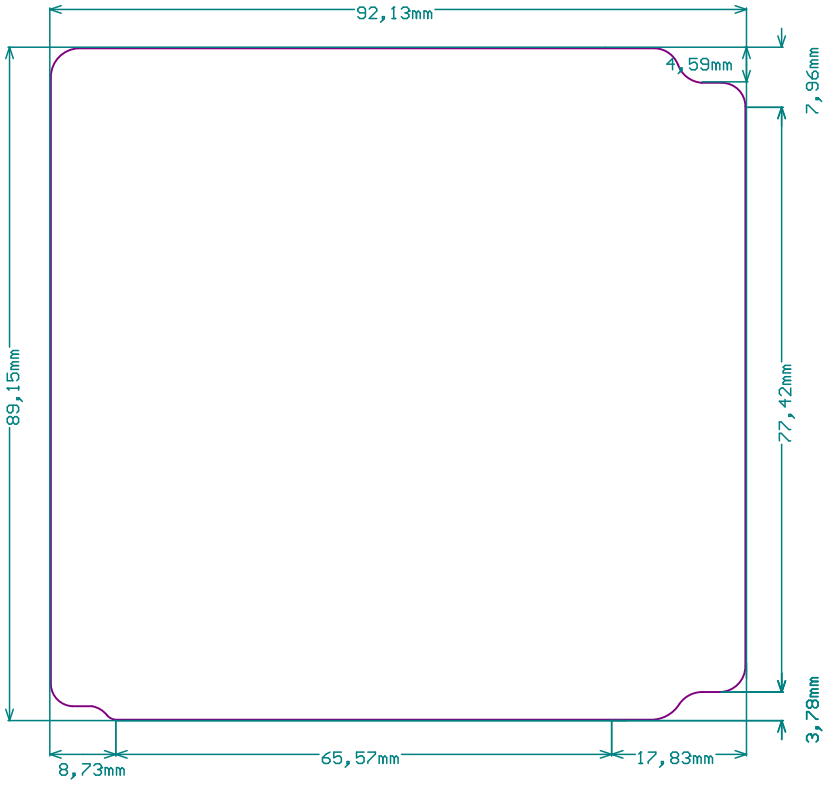
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Batteries Board 2.0		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

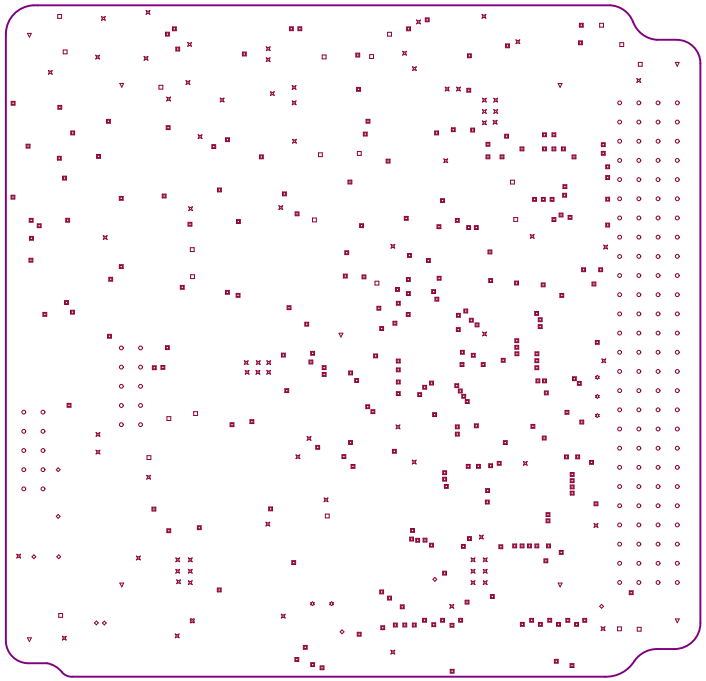
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Dimension		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
⊠	1	0,600mm (23,62mil)	PTH	Round	Top Layer - Bottom Layer	Via
✡	5	0,991mm (39,00mil)	PTH	Round	Top Layer - Bottom Layer	Pad
◇	9	0,381mm (15,00mil)	PTH	Round	Top Layer - Bottom Layer	Via
▽	9	3,200mm (125,98mil)	PTH	Round	Top Layer - Bottom Layer	Pad
□	24	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad
⌘	77	0,711mm (28,00mil)	PTH	Round	Top Layer - Bottom Layer	Via
○	124	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad
◙	253	0,300mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via
	502 Total					

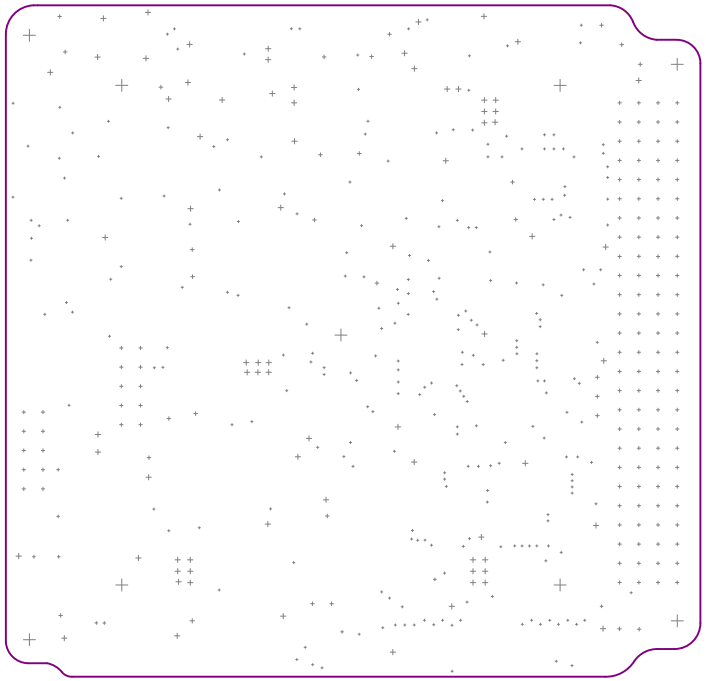
Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Drill Drawing		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,110mm	4,2	
5	Signal Layer 1	Copper	0,035mm		
6	Core	FR-4	1,200mm	4,2	
7	Signal Layer 2	Copper	0,036mm		
8	Dielectric 2		0,110mm	4,2	
9	Bottom Layer	Copper	0,035mm		
10	Bottom Solder	Solder Resist	0,010mm	3,5	
11	Bottom Overlay				

Fabrication specifications:

- Copper base 1OZ:
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom avaliable
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: EPS2		
Layer: Drill Guide		
Designed by: Andre M. P. Mattos (based on FSat-I EPS)		Project Code: EPS2
Date: 16/06/2021	Version: v0.2	Size: A4